

**8 Leads - UTDFN**  
**Package Material Declaration**



Date	31-Mar-21	Product name	Integrated Circuit
Package Code	LQ	RoHS Compliant	Y
Package Name	Ultra Thin Leadframe Package Double	Halogen Free	Y
Product Total Mass (g)	0.0063	Plating	NiPdAu

<b>Product Number</b>	MLX90392
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**Material Declaration**

Part Name	Material Name	Component Weight (g)	Material Component (Element)	CAS #	Element ratio (%)	Material Weight (g)	Ratio total Wt (ppm)
Leadframe	Copper Alloy C7025, NiPdAu plated	0.0028	Copper (Cu)	7440-50-8	94.65	0.00267	424075
			Silicon (Si)	7440-21-3	0.52	0.00001	2330
			Nickel (Ni)	7440-02-0	3.43	0.00010	15368
			Magnesium (Mg)	7439-95-4	0.13	0.000004	582
			Nickel (Ni)	7440-02-0	1.15	0.00003	5153
			Palladium (Pd)	7440-05-3	0.1	0.000003	448
			Gold (Au)	7440-57-5	0.020	0.0000006	90
Die	Silicon	0.0003	Silicon (Si)	7440-21-3	99.99	0.00034	54014
			others	-	0.01	0.00000003	5
IMC	S-FeNi-8	0.000012	Iron (Fe)	7439-89-6	19.75	0.000002	377
			Nickel (Ni)	7440-02-0	40	0.000005	763
			Molybdenum (Mo)	7439-98-7	40	0.000005	763
			others	-	0.25	0.00000003	5
Die attach material	Epoxy Adhesive QMI519	0.0002	Silver (Ag)	7440-22-4	80	0.00012	19066
			Bismaleimide resin	-	19.75	0.00003	4707
			Further Additives	-	0.25	0.00000038	60
Wire	Gold with Palladium	0.00002	Gold (Au)	7440-57-5	99	0.00002	3460
			Palladium (Pd)	7440-05-3	1	0.0000002	35
Encapsulation	Silica EP EME G770HCD	0.0030	Silica fused	60676-86-0	76.5	0.00226	358556
			Silicon dioxide	7631-86-9	15.2	0.00045	71242
			Epoxy Resin	-	3.9	0.00012	18279
			Phenol Resin	-	3.9	0.00012	18279
			Carbon Black	1333-86-4	0.5	0.00001	2344

**Total package weight (g)** 0.0063

**Comments**

- Composition derived from MSDS and material CoC from vendors
- Component weight based on assembly of generic parts
- Reliability qualification reports are available upon request through the appropriate sales or marketing contact
- Third party testing for RoHS substances are available upon request to environment@melexis.com

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